

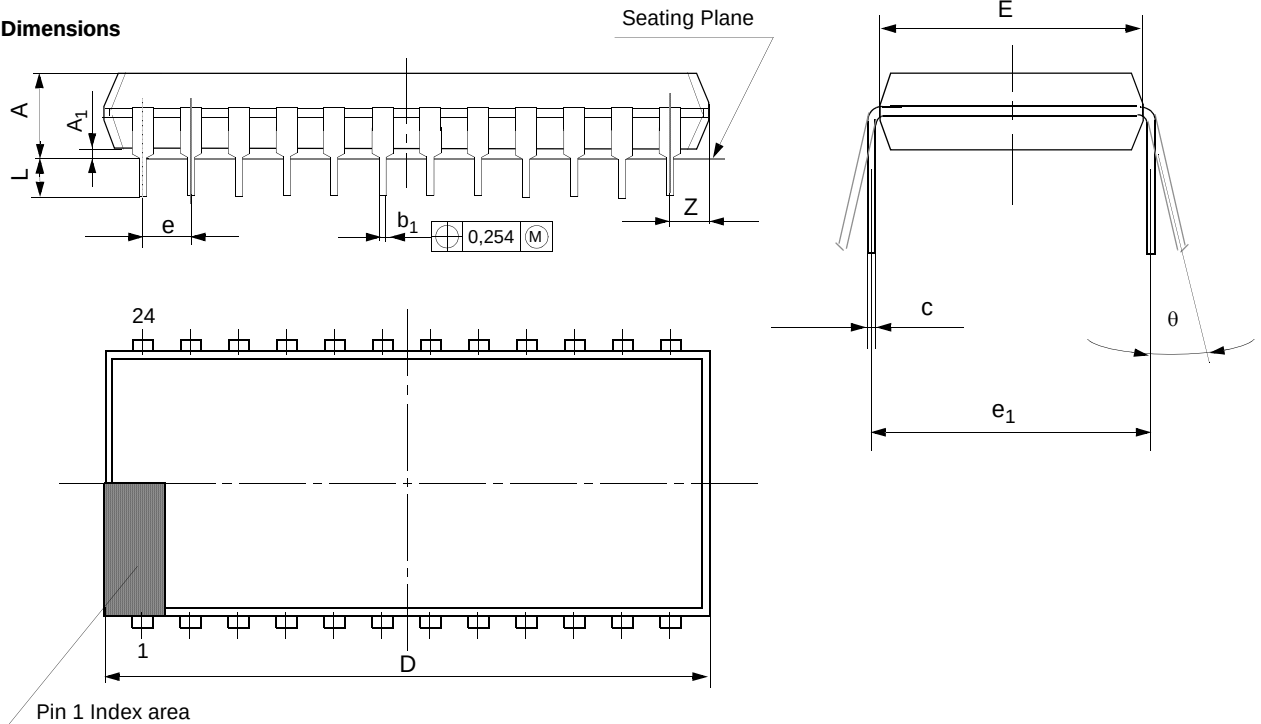
	Package PDIP24 (600 mil)	MDS 712
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Supersedes
Edition 11.95

Dimensions in millimetres

Based on IEC 191-2N: Type 051G03

1 Dimensions



Dimensions of Sub-Group B1	
$A_{\max}$	5,10
$A_{1\min}$	0,38
$b_{1\min}^{**}$	0,35
$b_{1\max}^{**}$	0,59
$c_{\min}$	0,20
$c_{\max}$	0,36
e_{nom}	2,54
$e_{1\text{nom}}$	15,24
$E_{\min}^*$	13,60
$E_{\max}^*$	14,30
$L_{\min}$	2,60
$Z_{\max}$	2,54

Dimensions of Sub-Group C1	
$A_{\min}$	3,00
$A_{1\max}$	1,80
$L_{\max}$	5,00
$D_{\min}^*$	31,50
$D_{\max}^*$	32,40
$\theta_{\min}$	0°
$\theta_{\max}$	15°

* without mold-flash

** The lead position tolerance requires slots with a minimum diameter of 0,7mm. The spacing between adjacent slots is 2,54mm.

- 2 Weight** $\leq 3,5 \text{ g}$
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating

Zentrum Mikroelektronik Dresden AG		
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